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*Amendment*

*RF 10-803*

Amendments to the Claims

Claim 1 (currently amended): A process for producing a predetermined area with two adjacent regions in an integrated semiconductor such that a first region of the two adjacent regions has a target concentration of a dopant that is lower than a target concentration of the dopant in a second region of the two adjacent regions, the process which comprises:

applying a polysilicon layer to a semiconductor blank;

forming a window in the polysilicon layer such that the window defines a predetermined area of the semiconductor blank;

doping the predetermined area of the semiconductor blank with the dopant until a concentration of the dopant is at least as high as the target concentration of the second region;

forming a spacer in a self-adjusting manner with respect to an edge of the window such that the spacer defines the ~~second~~ first region; and

diffusing the dopant outward from the first region until the concentration of the dopant corresponds to the target concentration of the first region.

Claim 2 (original): The process according to claim 1, which comprises performing the doping by implantation.

Claim 3 (original): The process according to claim 2, which comprises: after the doping step and before forming the spacer, tempering the predetermined area.

Claim 4 (original): The process according to claim 3, which comprises performing outward diffusion by tempering until a concentration of the dopant corresponds to the target concentration of the second region.

Claim 5 (original): The process according to claim 1, wherein the dopant is selected from the group consisting of boron, aluminum, gallium, indium, phosphorus, arsenic, and antimony.

Claim 6 (original): The process according to claim 1, wherein the step of diffusing the dopant outward is performed by tempering.

Claim 7 (original): The process according to claim 1, which comprises providing the predetermined area as a base area of a transistor.

Claim 8 (original): The process according to claim 7, which comprises providing the first region as a base region of an active transistor.

Claim 9 (original): The process according to claim 8, which comprises providing the second region as a link region between a base region and a polysilicon track.

Claim 10 (original): The process according to claim 7, which comprises providing the second region as a link region between a base region and a polysilicon track.

Claim 11 (original): The process according to claim 1, which comprises: after the doping step and before forming the spacer, tempering the predetermined area.

Claim 12 (original): The process according to claim 1, which comprises:

producing an integrated transistor, in which the second region forms a base area underneath a spacer surrounding an emitter; and

the first region forms a base area under the emitter.

Claim 13 (withdrawn): An integrated transistor, comprising:

an emitter, a collector, and a base;

a polysilicon layer provided as a base contact, said polysilicon layer having an edge; and

a spacer formed on said edge of said polysilicon layer and surrounding said emitter;

said base having a base area under said spacer and a base area under said emitter;

said base area under said spacer being more highly doped than said base area under said emitter;

said base area under said spacer being formed in a self-adjusting manner in relation to said spacer.